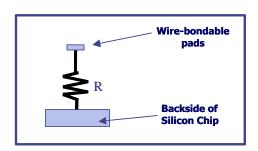
Thin Film Back-Contact Silicon Resistor Chip

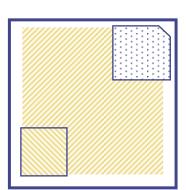
SiliconApps SATX is a miniature back-contact silicon resistor network with a chip size of 20 x 20 mils sq. Conductive epoxy or eutectic die-attachment to an active substrate area eliminates the need for a second wire bond. This silicon resistor chip is built using the high reliable Tantalum Nitride resistor material. This product offers a very high degree of stability, extremely low Temperature Coefficient of Resistance and exceptionally low noise.

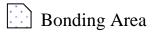
| Electrical Specifications | | | | | | |
|---------------------------------------|--|---------------------------|-----|--|--|--|
| Parameter | Conditions | | | | | |
| Temperature Coefficient of Resistance | -55°C to 125°C | ±250ppm/°C | Max | | | |
| Operating Voltage | -55°C to 125°C | 100Vdc | Max | | | |
| Power Rating (per resistor) | @ 70°C (Derate linearly to zero @ 150°C) | 250mw | Max | | | |
| Thermal Shock | Method 107 MIL-STD-202F | ±0.5% @ΔR | Max | | | |
| High Temperature Exposure | 100 Hrs @ 150°C Ambient | ±0.25% ΔR | Max | | | |
| Moisture Resistance | Method 106 MIL-STD-202F | ±0.5% ΔR | Max | | | |
| Life | Method 108 MIL-STD-202F (125°C/1000 hr) | ±0.5% ΔR | Max | | | |
| Noise | Method 308 MIL-STD-202F upto 250 KΩ | -25dB | Max | | | |
| | ≥250 KΩ | -20dB | | | | |
| Insulation Resistance | @ 25°C | $1 \times 10^{12} \Omega$ | Min | | | |



| Mechanical Specifications | | | | |
|---------------------------|--|--|--|--|
| Substrate | Silicon 10±2 mils thick | | | |
| Isolation Layer | SiO ₂ 10,000Å thick, min | | | |
| Backing | Lapped (gold optional) | | | |
| Metalization or Pad | Aluminium 10,000Å thick, min (15,000Å gold optional) | | | |

| Values | |
|--|--|
| From 10Ω to 1 meg Ω for each resistor. | |





Packaging Two inch square trays of 400 chips maximum is standard.

Format

Die Size: 20±3 mils square Bonding Pads: 4x4 mils

typical

Notes Resistor pattern may vary from one value to another.

Notes: 1. This document supercedes all previous specifications.

2. Specifications are subject to change without notice or obligation.

| Part Number Designation | | | | | | | |
|-------------------------|--|----------------|--|-----------------------|--|--|--|
| SATX | 6802 | F | TCR | Bond Pad | | | |
| Series | Value | Tolerance* | $A = \pm 50 \text{ppm/}^{\circ}\text{C}$ | No Letter = Aluminium | | | |
| | First 3 digits are significant value. Last digit represents number of zeros (Ex: 1001 = 1k-ohms). R indicates decimal point. | F = ±1% | $H = \pm 100 ppm/^{\circ}C$ | G = Gold | | | |
| | | G = ±2% | No letter = ±250ppm/°C | | | | |
| | | J = ±5% | | | | | |
| | | K = ±10% | | | | | |
| | | $M = \pm 20\%$ | | | | | |